

AMENDMENTS TO THE SPECIFICATION:

Page 36, please replace the paragraph beginning on line 12 with the following rewritten paragraph:

--The semi-finished semiconductor devices contains a plurality of input/output buffers formed in the chip area 12', and the conductive leads 60' and [[90]] 92 are suitably and electrically connected to the input/output buffers through the intermediary of via-holes formed in the insulation layers 38', 42', 50', and 54'. Referring to Fig. 16, an electrical connection of the conductive lead [[90]] 92 to an active region 34' of the input/output buffer through a via-hole 46' is representatively shown by way of example.--